

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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3-terminal Filters, SMD Array

For differential signal line (UHF band terrestrial digital broadcast / DVB-H band compatible)

MEA-LE Series

MEA1608LE Type

MEA1608LE

1608[0603 inch]*

* Dimensions Code JIS[EIA]

REMINDERS FOR USING THESE PRODUCTS

Before using these products, be sure to request the delivery specifications.

SAFETY REMINDERS

Please pay sufficient attention to the warnings for safe designing when using these products.

♠ REMINDERS					
 The storage period is less than 12 months. Be sure to follow the storage conditions (Temperature: 5 to 40°C, Humidity: 10 to 75% F or less). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. 	₹Н				
Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).					
Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.	;				
Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.					
When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.	0				
Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.					
Carefully lay out the coil for the circuit board design of the non-magnetic shield type. A malfunction may occur due to magnetic interference.					
Use a wrist band to discharge static electricity in your body through the grounding wire.					
Do not expose the products to magnets or magnetic fields.					
Do not use for a purpose outside of the contents regulated in the delivery specifications.					
The products listed on this catalog are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to					
society, person or property.					
If you intend to use the products in the applications listed below or if you have special requirements exceeding the range or condition	ns				

- (1) Aerospace/Aviation equipment
- (2) Transportation equipment (cars, electric trains, ships, etc.)
- (3) Medical equipment
- (4) Power-generation control equipment

set forth in the each catalog, please contact us.

- (5) Atomic energy-related equipment
- (6) Seabed equipment
- (7) Transportation control equipment

- (8) Public information-processing equipment
- (9) Military equipment
- (10) Electric heating apparatus, burning equipment
- (11) Disaster prevention/crime prevention equipment
- (12) Safety equipment
- (13) Other applications that are not considered general-purpose applications

When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.

EMC Components



3-terminal Filters, SMD Array

Product compatible with RoHS directive
Halogen-free
Compatible with lead-free solders

For differential signal line

(UHF band terrestrial digital broadcast / DVB-H band compatible)

Overview of MEA1608LE Type

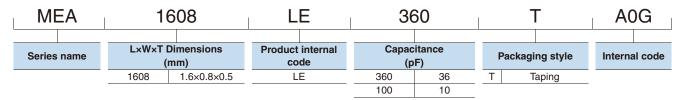
FEATURES

- LC filter with dual circuit formation differential lines (D+ and D−) for high-density mounting.
- O Low profile type with a thickness of 0.5mm.
- Ocan reduce radiation noise generated from differential signal lines (LVDS, MIPI, MDDI).
- Effective as a desensitization countermeasure for digital terrestrial broadcasts (UHF band).

APPLICATION

Noise removal for differential transmission lines (MIPI, etc.) of various mobile devices.

PART NUMBER CONSTRUCTION



■ OPERATING TEMPERATURE RANGE, PACKAGE QUANTITY, PRODUCT WEIGHT

	Temperature range		Package quantity	Individual weight
Туре	Operating temperature	Storage temperature*		
	(°C)	(°C)	(pieces/reel)	(mg)
MEA1608LE	-40 to +85	-40 to +85	4,000	3.5

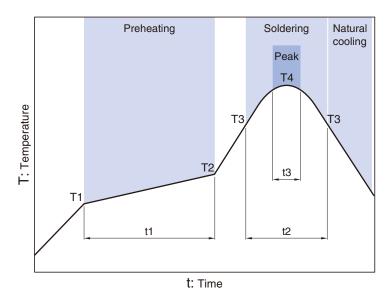
^{*} The Storage temperature range is for after the circuit board is mounted.

RoHS Directive Compliant Product: See the following for more details related to RoHS Directive compliant products. http://product.tdk.com/en/environment/rohs/

O Halogen-free: Indicates that CI content is less than 900ppm, Br content is less than 900ppm, and that the total CI and Br content is less than 1500ppm.



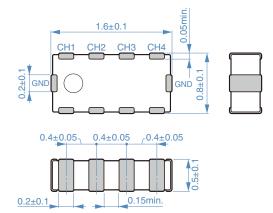
■ RECOMMENDED REFLOW PROFILE



Preheating		Soldering	9	Peak	Peak	
Temp.		Time	Temp.	Time	Temp.	Time
T1	T2	t1	Т3	t2	T4	t3
150°C	180°C	60 to 120s	230°C	30 to 60s	250 to 260°C	10s max.

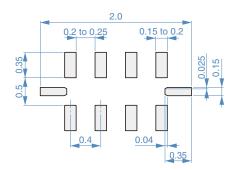


■SHAPE & DIMENSIONS



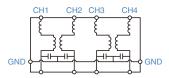
Dimensions in mm

■ RECOMMENDED LAND PATTERN



Dimensions in mm

CIRCUIT DIAGRAM





ELECTRICAL CHARACTERISTICS

CHARACTERISTICS SPECIFICATION TABLE

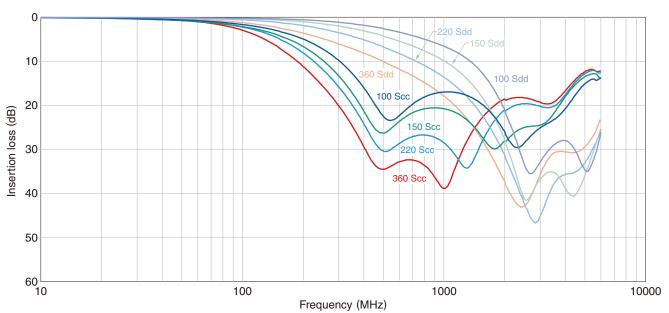
Capacitance	Cutoff frequency	Insertion loss 20dB frequency range	Rated voltage	Rated current	Part No.
(pF)	(MHz)typ.	(MHz)	(V)max.	(mA)max.	
36	180(Sdd)		6.3	50	MEA1608LE360TA0G
22	270(Sdd)		6.3	50	MEA1608LE220TA0G
15	390(Sdd)		6.3	50	MEA1608LE150TA0G
10	550(Sdd)		6.3	50	MEA1608LE100TA0G

O Measurement equipment

Measurement item	Product No.	Manufacturer
Frequency characteristics	N5230C	Agilent Technologies

^{*} Equivalent measurement equipment may be used.

☐ INSERTION LOSS VS. FREQUENCY CHARACTERISTICS



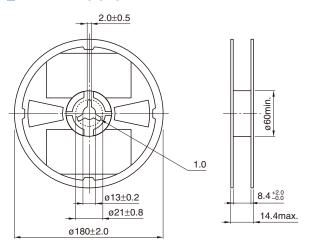
 \bigcirc Measurement equipment

Product No.	Manufacturer
N5230C	Agilent Technologies

^{*} Equivalent measurement equipment may be used.

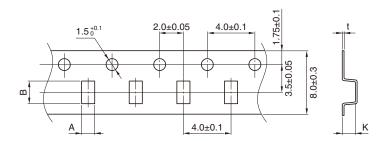
■PACKAGING STYLE

□REEL DIMENSIONS



Dimensions in mm

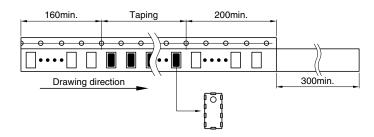
TAPE DIMENSIONS



Dimensions in mm

K t

Type	Α	В	K	t
MEA1608LE	1.00±0.10	1.80±0.10	1.0max.	0.25±0.05



Dimensions in mm